

IN THE CLAIMS:

Claims 3, 6, 7 and 8 have been amended herein. New claims 10 through 14 have been added. Please note that all claims currently pending and under consideration in the referenced application are shown below, in clean form, for clarity. Please enter these claims as amended. Also attached is a version with markings to show changes made to the claims.

1. (Previously Amended) A memory module, comprising:
a substrate;
at least two sites on said substrate, each of said at least two sites having mounted thereon a memory chip with substantially the same memory capacity, said memory chips providing a memory capacity for said memory module; and
at least one other site on said substrate for mounting at least one additional memory chip thereon, said at least one additional memory chip having a functional memory less than said memory capacity of said memory module.
2. (Previously Amended) A memory module, comprising:
a substrate;
at least two sites on said substrate, each of said at least two sites having mounted thereon a memory chip with substantially the same memory capacity, said memory chips providing a memory capacity for said memory module; and
at least one other site on said substrate configured to accept either of at least two other memory chips of different sizes.

3. (Twice Amended) A memory module, comprising:
a substrate having a plurality of memory chips individually mounted thereon; and
a programmable device adapted to reroute input and output paths to and from said plurality of memory chips to bypass nonfunctional memory in at least one of said plurality of memory chips, extending to one or more additional individual locations on said substrate and configured to incorporate functional memory of one or more additional chips disposed at said one or more additional individual locations on said substrate into said rerouted input and output paths.
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4. (Previously Amended) The memory module of claim 3, further comprising at least one additional memory chip mounted on at least one of said additional locations, operably coupled to said programmable device and providing functional memory in an amount equivalent to or greater than said nonfunctional memory.
5. (Previously Amended) The memory module of claim 4, wherein said at least one additional memory chip contains at least some nonfunctional memory.
6. (Twice Amended) The memory module of claim 4, wherein said at least one additional memory chip comprises at least two memory chips having different memory capacity and being placed at different additional individual locations.
7. (Twice Amended) The memory module of claim 3, wherein said programmable device comprises an EEPROM.

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8. (Twice Amended) A memory module comprising:
a plurality of chips individually mounted to a substrate, said plurality of chips collectively exhibiting an amount of nonfunctional memory exceeding a memory capacity of any one chip of said plurality; and
at least one additional memory chip individually mounted to said substrate providing an amount of functional memory equal to or greater than said amount of nonfunctional memory.

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9. The module of claim 8, wherein said at least one additional memory chip comprises at least two memory chips having different amounts of functional memory.
Please add the following new claims:

10. (New) The memory module of claim 5, wherein said at least one additional memory chip contains an amount of functional memory substantially equal to an amount of nonfunctional memory in said at least one of said plurality of memory chips.

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11. (New) The memory module of claim 4, wherein said at least one additional memory chip contains an amount of functional memory substantially equal to an amount of nonfunctional memory in said at least one of said plurality of memory chips.

12. (New) The memory module of claim 8, wherein said at least one additional memory chip provides an amount of functional memory substantially equal to said amount of nonfunctional memory collectively exhibited by said plurality of memory chips.

13. (New) The memory module of claim 8, wherein said at least one additional memory chip contains at least some nonfunctional memory.

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14. (New) The memory module of claim 13, wherein said at least one additional memory chip provides an amount of functional memory substantially equal to said amount of nonfunctional memory collectively exhibited by said plurality of memory chips.
